

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-35 (canceled).

Claim 36 (currently amended): A device transfer method comprising:

embedding a plurality of first~~one-side~~ devices into an uncured pressure sensitive adhesive layer provided on a ~~second-first~~ substrate such that the plurality of first devices penetrate the surface of the uncured pressure sensitive adhesive layer;

embedding ~~other-side~~a plurality of second devices arranged on a ~~first-second~~ substrate into the uncured pressure sensitive adhesive layer provided on the ~~second-first~~ substrate by positioning the first and second substrates in close proximity thereof such that the plurality of second devices arranged on the second substrate penetrate the surface of the uncured pressure sensitive adhesive layer; and~~wherein the other-side devices and one-side devices are light emitting diodes having different characteristics; and~~

stripping the other-side~~plurality of second~~ devices from the ~~first-second~~ substrate while the pressure sensitive adhesive layer is in an uncured state thereby holding the ~~other-side~~plurality of first and second devices in an embedded state within the uncured pressure sensitive adhesive layer, wherein the first devices and second devices are light emitting diodes having different characteristics.

Claim 37 (canceled).

Claim 38 (currently amended): The device transfer method as set forth in claim 36, wherein the ~~one-side~~plurality of first devices and the ~~other-side~~plurality of second devices are held in the embedded state in different areas on the first substrate.

Claim 39 (currently amended): A method of manufacturing a display apparatus comprising:

embedding devices arranged on a first substrate into an uncured pressure sensitive adhesive layer provided on a second substrate by positioning the first and second substrates in close proximity thereof such that the devices arranged on the first substrate penetrate the surface of the uncured pressure sensitive adhesive layer, wherein the devices are light emitting diodes, ~~the pressure sensitive adhesive layer being in an uncured state;~~

stripping the devices from the first substrate while the pressure sensitive adhesive layer is in an uncured state thereby holding the devices in an embedded and uncured state within the pressure sensitive adhesive layer,

hardening the pressure sensitive adhesive layer to cure the pressure sensitive adhesive layer;

forming first electric wirings on the pressure sensitive adhesive layer, adhering a third substrate onto a side on which the first electric wirings are formed of the pressure sensitive adhesive layer, and stripping the second substrate and the pressure sensitive adhesive layer from each other; and

providing the pressure sensitive adhesive layer with openings reaching the devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer.

Claim 40 (previously presented): The method of manufacturing a display apparatus as set forth in claim 39, wherein display is carried out through simple matrix driving by impressing a voltage on the devices through the first electric wirings and the second electric wirings.

Claim 41 (currently amended): A method of manufacturing a display apparatus comprising:

~~embedding one-side a plurality of first devices arranged on a first substrate into an uncured pressure sensitive adhesive layer provided on a second substrate; the pressure sensitive adhesive layer being in an uncured state by positioning the first and second substrates in close proximity thereof such that the plurality of first devices arranged on the first substrate penetrate the surface of the uncured pressure sensitive adhesive layer;~~

~~stripping the one-side plurality of first devices from the first substrate while the pressure sensitive adhesive layer is in an uncured state thereby holding the one-side plurality of first devices in an embedded and uncured state within the pressure sensitive adhesive layer;~~

~~further embedding other-side a plurality of second devices arranged on the first substrate into the uncured pressure sensitive adhesive layer; the pressure sensitive layer being remaining in an uncured state by positioning the first and second substrates in close proximity thereof such that the plurality of second devices arranged on the first substrate penetrate the surface of the uncured pressure sensitive adhesive layer;~~

~~stripping the other-side plurality of second devices from the first substrate while the pressure sensitive adhesive layer is in an uncured state thereby holding the other-side plurality of second devices in an embedded and uncured state within the pressure sensitive adhesive layer, where the one-side plurality of first devices are embedded in the uncured pressure sensitive adhesive layer, and wherein the one-side devices and other-side devices are light emitting diodes;~~

~~hardening the pressure sensitive adhesive layer to cure the pressure sensitive adhesive layer where the one-side plurality of first devices and the other-side plurality of second devices are held in an embedded and cured state within the pressure sensitive adhesive layer;~~

~~forming first electric wirings on the pressure sensitive adhesive layer, adhering a third substrate onto the side on which the first electric wirings are formed of the pressure sensitive layer, and stripping the second substrate and the pressure sensitive adhesive layer from each other; and~~

~~providing the pressure sensitive adhesive layer with openings reaching the one-side plurality of first devices or the other-side plurality of second devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer, wherein the first devices and second devices are light emitting diodes.~~

Claim 42 (currently amended): The method of manufacturing a display apparatus as set forth in claim 41, wherein the ~~one-side~~first devices and the ~~other-side~~second devices have different characteristics.

Claim 43 (currently amended): The method of manufacturing a display apparatus as set forth in claim 41, wherein the ~~one-side~~plurality of first devices and the ~~other-side~~plurality of second devices are held in the embedded state in different areas on the second substrate.

Claim 44 (currently amended): The method of manufacturing a display apparatus as set forth in claim 41, wherein display is carried out through simple matrix driving by impressing a voltage on the ~~one-side~~plurality of first devices or the ~~other-side~~plurality of second devices through the first electric wirings and the second electric wirings.

Claim 45 (currently amended): The method of manufacturing a display apparatus as set forth in claim 41, wherein any one of the ~~one-side~~plurality of first devices and the ~~other-side~~plurality of second devices are any one of display devices and driving circuit devices.

Claim 46 (previously presented): The method of manufacturing a display apparatus as set forth in claim 45, wherein display is carried out through active matrix driving by impressing a voltage on the display devices by the driving circuit devices.

Claim 47 (currently amended): The device transfer method as set forth in claim 36, further comprising bringing the ~~other-side~~plurality of second devices into contact with a temporary adhesion layer provided on the ~~first-second~~ substrate for temporarily adhering the devices to the temporary adhesion layer thereby arranging the devices on the ~~first-second~~ substrate, before embedding the ~~other-side~~plurality of second devices into the uncured pressure sensitive adhesive layer provided on the ~~second-first~~ substrate.

Claim 48 (currently amended): The device transfer method as set forth in claim 47, wherein a tack of the pressure sensitive adhesive layer provided on the ~~second-first~~ substrate is greater than a tack of the temporary adhesion layer provided on the ~~first-second~~ substrate.

Claim 49 (previously presented): The device transfer method as set forth in claim 48, wherein the tack of at least one of the uncured pressure sensitive adhesive layer and the temporary adhesion layer is changed so that the tack of the uncured pressure sensitive adhesive layer will be greater than the tack of the temporary adhesion layer.

Claim 50 (previously presented): The device transfer method as set forth in claim 36, further comprising curing the uncured pressure sensitive adhesive layer using a heating treatment.

Claim 51 (previously presented): The method of manufacturing a display apparatus of claim 39, wherein the uncured pressure sensitive adhesive layer is hardened after stripping the devices from the first substrate.